

Quantitative EL image analysis towards thermo-electro-mechanical simulations in solar cells

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Outline

Damage, micro-cracks, and other defects introduced in PV modules are important features impacting on their electrical power-loss, their actual solar conversion efficiency and also their lifetime. The aim of this work is to perform quantitative analysis of electroluminescence (EL) images of solar cells through two models: a distributed two-dimensional model and a one-dimensional one. The proposed improvement, with respect to the approaches available in the literature, represents a fundamental step towards the development of an innovative fully coupled thermo-electro-mechanical numerical method.

Distributed circuit for series resistance and current identification



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Simulation of a cell operating during an EL test: each series resistance is an equivalent one and takes into account all different resistances (emitter, contact, metallization)¹. Using Kirchhoff's law, the I-V equation for each discretized node is given by:

Results for monocrystalline Si cells

The parameters used for the simulations are: $I_{sc} = 0$, $R_{loc} = 0.2 \ \Omega \text{cm}^2$, $V_T = 25 \text{ mV}$, $\rho_{\rm S} = 0.13 \ \Omega/{\rm cm}, \ I_{01} = 1.48 \times 10^{-12} \ {\rm mA/cm^2}.$

 V_0 and R_{cr} are free parameters used to fit the EL experimental data and to obtain the same voltage in correspondence of the two busbars, at x = 0 and x = d.





circuit.

The simulation aims at computing average values for I with discrete homogeneous resistance. The series resistance value to be identified is determined from Eq. (1) according to a Netwon-Raphson method² due to the nonlinearity of the equation. Performing this procedure for different EL images, a lookup table relating the type of defects and the spatial distribution of resistances can be build up.



FIG. 2. (a) EL image of a damaged polycrystalline Silicon cell and (b) EL intensity (a.u.) of the examined area identified in Fig. 2(a) by a yellow rectangle.

FIG. 3. (a) Identified resistances (Ω) and (b) predicted current (A) from the nonlinear identification procedure.

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One-dimensional model for current distribution

The model proposed in Ref. 3 aims at simulation current and voltage as a function of the series resistance:



FIG. 5. Vertical current for a cell with a crack, across the section, unloaded condition. R_{cr} =0.096 Ω cm², V_0 =0.579 V.



FIG. 7. Vertical current and voltage corresponding to Fig. 5, in loaded condition R_{cr} =0.22 Ω cm², V_0 =0.580 V.

FIG. 6. Voltage for the cell shown in Fig. 5, unloaded condition.



FIG. 8. Vertical current and voltage for a cell with two cracks, loaded condition. R_{cr1} =1.13 Ω cm² R_{cr2} =0.48 Ω cm² V_0 =0.572 V.

Results for polycrystalline Si cells

The parameters are: $I_{sc} = 0$, $V_T = 25$ mV, $\rho_S = 0.13 \ \Omega/cm$, $I_{01} = 1.48 \times 10^{-12} \text{ mA/cm}^2$. To obtain R_{loc} , the pseudo-random value dR has been chosen as a percentage of \overline{R} , which is set equal to $0.5 \ \Omega \text{cm}^2$. V_0 and R_{cr} have been varied to obtain an appropriate fit of experimental data and to have the same voltage in correspondence of the two busbars.



FIG.4. Schematic representation of investigated area with I_{ν} and I_{h} vertical and horizontal current density, respectively.

 $\frac{\partial^2 V(x)}{\partial^2 r} = V''(x) = \rho_s I_v(x)$

The integration path from x = 0 to x = d is divided into fractions of length dx. Between x and x + dx, I_{v} is constant and, therefore, the voltage assumes a quadratic trend governed by the following ordinary differential equations:

 $I_h(x + dx) = I_h(x) + I_v(x)dx$ V'(x + dx) = V'(x) + V''(x)dx $V(x + dx) = V(x) + V'(x)dx + \frac{V''}{2}dx^{2}$

Generalization of the model in case of cracks

The previous electric model is modified by including localized resistances due to the presence of cracks crossing Si cells and/or fingers. This allows the coupling between the thermo-mechanical field and the electric one. The electric model presented is modified including a voltage discontinuity, dependent on the relative crack opening displecement at crack faces. This discontinuity, proportional to the crack resistance R_{cr} and to the horizontal current $J_h(x)$, may be written as:

 $V(x)=V(x)+R_{cr}J_h(x).$





in Fig. 11.

Conclusions

- > The extension of the one-dimensional model for current distribution to the presence of cracks allows considering the coupling between thermo-mechanical field and electric one.
- The proposed method can be used to interpret the relation between voltage discontinuity and crack opening displacement at crack faces.

Monocrystalline Si cells

The connection between discontinuity R_{cr} and relative crack opening displacement at crack faces has been analysed in monocrystalline-Si using bending tests on a semi-flexible rectangular PV module⁴ (made of two rows of 5 monocrystalline cells). Tests have been performed in the laboratory by monitoring cracking at different deformation levels by EL imaging. In the model, R_{cr} depends on crack opening. Therefore, it changes from loading to unloading case. For monocrystalline cells R_{loc} is equal to 0.2 Ω cm².

Polycrystalline Si cells

EL tests have been performed in the laboratory on undamaged and damaged modules after a sequence of environmental cycle tests. For polycristalline–Si, R_{loc} is dishomogeneous and depends on grain boundaries and defects. In order to quantify its variability from its average value, R_{loc} has been replaced with $\overline{R} + dR$, where \overline{R} is the average value and dR takes into account the fluctuations using pseudorandom values taken from a gaussian distribution with a prescribed variance.

- > In monocrystalline Si cells the influence of crack opening on the electric response is evident. In loaded conditions the value of R_{cr} significantly increases (Figs. 7, 8).
- > The polycristalline case is more complex due to a voltage fluctuation caused by the contemporary presence of defects and dishomogeneity of Si grains.
- \succ The amplitude of the variation term, dR, is about 30% of \overline{R} to match experimental tests.

References:

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Acknowledgments: ERC Starting Grant IDEAS 2011 Multi-field and Multi-scale Computational Approach to Design and Durability of PhotoVoltaic Modules- CA2PVM. FIRB Future in Research Project Structural Mechanics Models for Renewable Energy Applications (Italian Ministry of Education, University and Research, MIUR)